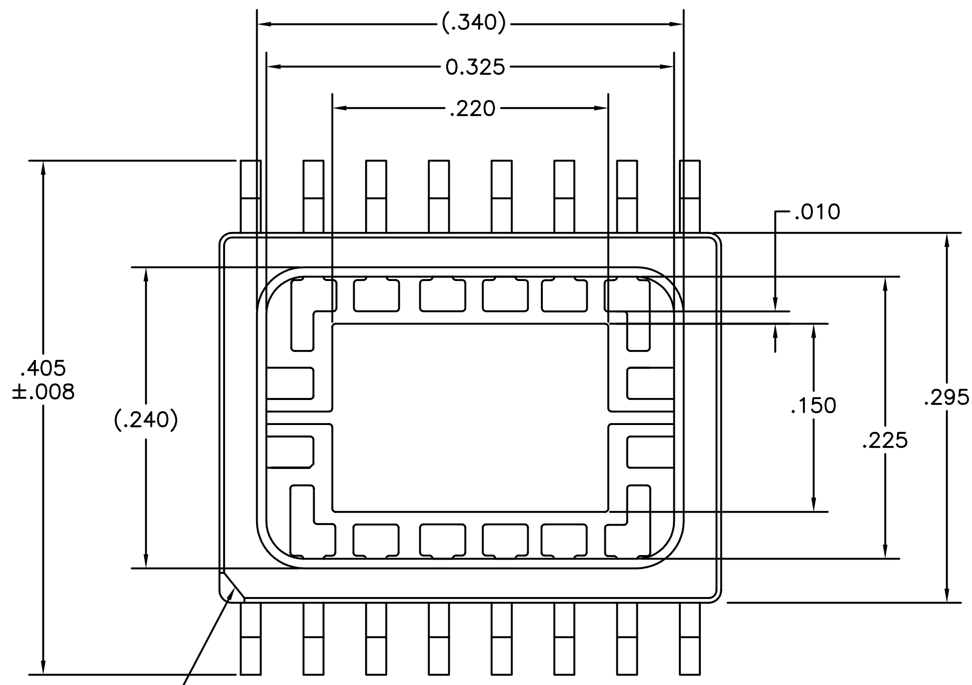
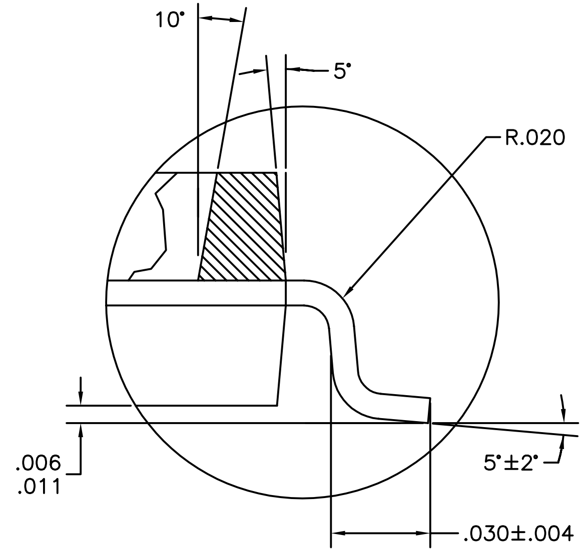
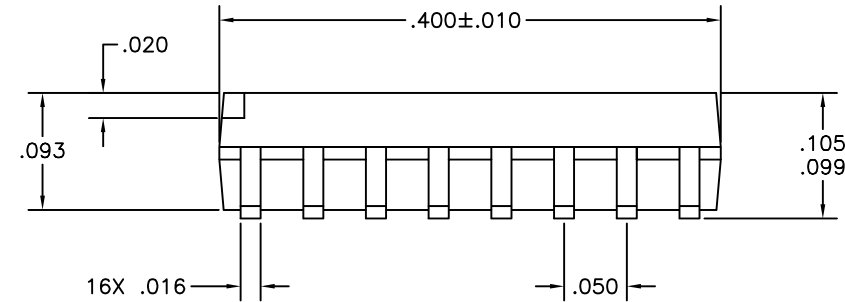
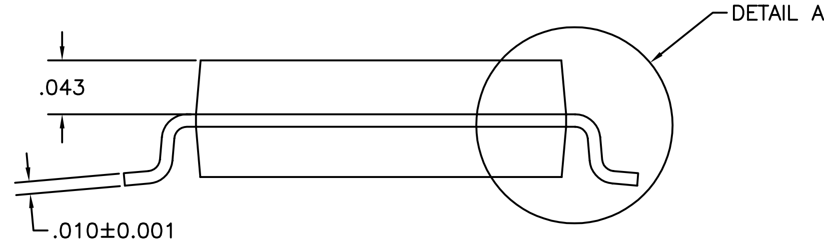
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10790	11/01/06	PRODUCTION RELEASE	D.BENANDO





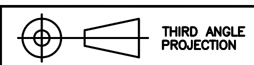
DETAIL A





NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL Au PLATE.
4. DIE PAD: 0.220 X 0.150
5. UNSPECIFIED RADIUS: R.010 MAX.
6. JEDEC OUTLINE: MS-013



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
X.XX ± 0.01 X.XXXX ±---
X.XXX ± 0.005 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	11/01/06
APP BY	P. FLASKERUD	DATE	11/01/06
CUSTOMER	---		

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16 Lead 300 mils SOIC Open-Pak

SIZE	PART NO.	REV
A	SOIC300-16-OP-01	3
SCALE NONE	CAD FILE SOIC300-16-OP-01-R3.DWG	SHEET 1 OF 1

BORDER-AHI-1.DWG
REV 1 ECN 10598